

# GBPC 12, 15, 25, 35 SERIES

## Bridge Rectifiers (Glass Passivated)

勝特力材料 886-3-5753170  
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 勝特力电子(深圳) 86-755-83298787  
[Http://www.100y.com.tw](http://www.100y.com.tw)

### Features

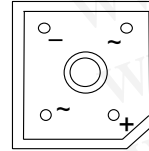
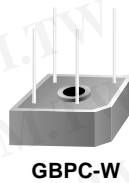
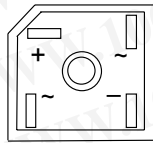
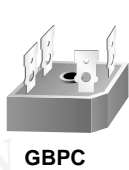
- Integrally molded heatsink provided very low thermal resistance for maximum heat dissipation.
- Surge overload ratings from 300 amperes to 400 amperes.
- Isolated voltage from case to lead over 2500 volts.
- UL certified, UL #E96005

### Suffix "W"

Wire Lead Structure

### Suffix "M"

Terminal Location Face to Face



### Absolute Maximum Ratings \* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value							Units
		005	01	02	04	06	08	10	
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
V <sub>RMS</sub>	Maximum RMS Bridge Input Voltage	35	70	140	280	420	560	700	V
V <sub>R</sub>	DC Reverse Voltage (Rated V <sub>R</sub> )	50	100	200	400	600	800	1000	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>A</sub> = 55°C								
	GBPC12	12							A
	GBPC15	15							A
	GBPC25	25							A
	GBPC35	35							A
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current GBPC12, 25, 25 8.3ms Single Half-Sine-Wave GBPC35	300							A
		400							A
T <sub>STG</sub>	Storage Temperature Range	-55 to +150							°C
T <sub>J</sub>	Operating Junction Temperature	-55 to +150							°C

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### Thermal Characteristics

Symbol	Parameter	Value	Units
P <sub>D</sub>	Power Dissipation	83.3	W
R <sub>θJL</sub>	Thermal Resistance, Junction to Lead	1.5	°C/W

### Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>F</sub>	Forward Voltage Drop, per bridge @6.0A @7.5A @12.5A @17.5A	GBPC12 GBPC15 GBPC25 GBPC35	1.1 (Max.) V
I <sub>R</sub>	Reverse Current, per element @ Rated V <sub>R</sub>	T <sub>A</sub> = 25°C T <sub>A</sub> = 125°C	5.0 (Max.) 500 (Max.) μA μA
	I <sup>2</sup> t Rating for Fusing t < 8.35ms	GBPC12, 15, 25 GBPC35	375 660 A <sup>2</sup> Sec A <sup>2</sup> Sec
C <sub>T</sub>	Total Capacitance, per leg V <sub>R</sub> = 4.0V f = 1.0MHz	GBPC12, 15, 25 GBPC35	180 200 pF pF

### Typical Performance Characteristics

Figure 1. Forward Current Derating Curve

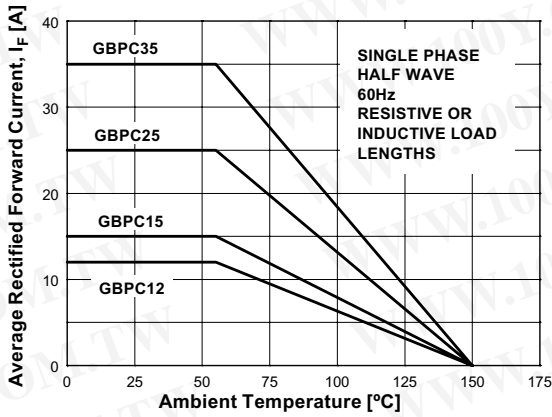


Figure 2. Non-Repetitive Surge Current

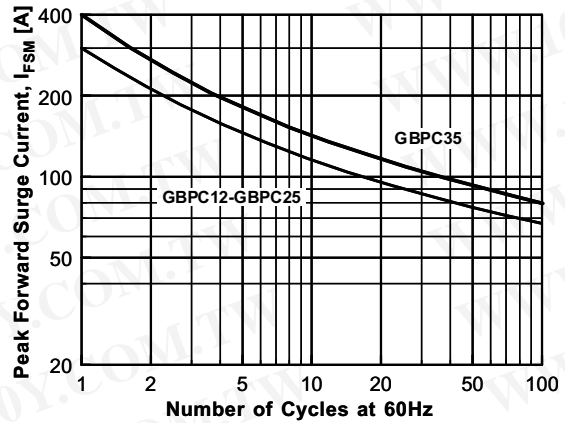


Figure 3. Forward Voltage Characteristics

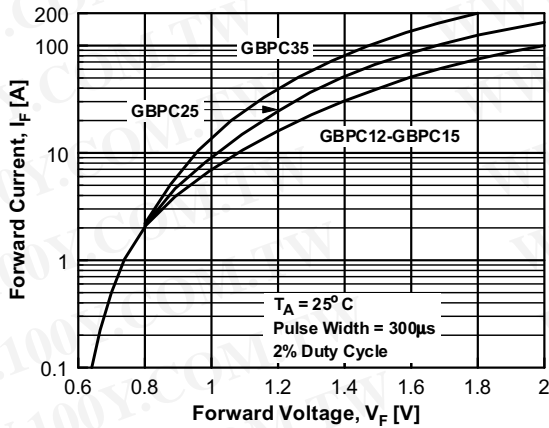
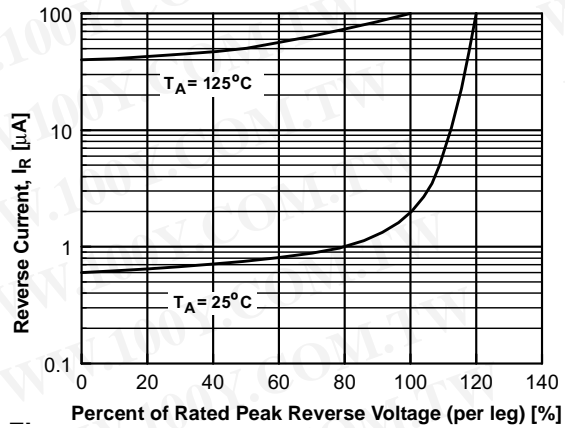


Figure 4. Reverse Current vs Reverse Voltage



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CROSSVOLT™	GlobalOptoisolator™	MicroPak™	QFET®	SuperSOT™-8
DOVE™	GTO™	MICROWIRE™	QS™	SyncFET™
EcoSPARK™	HiSeC™	MSX™	QT Optoelectronics™	TinyLogic®
E <sup>2</sup> CMOST™	I <sup>2</sup> C™	MSXPro™	Quiet Series™	TINYOPTO™
EnSigna™	i-Lo™	OCX™	RapidConfigure™	TruTranslation™
FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
FACT Quiet Series™		OPTOLOGIC®	μSerDes™	UltraFET®
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